

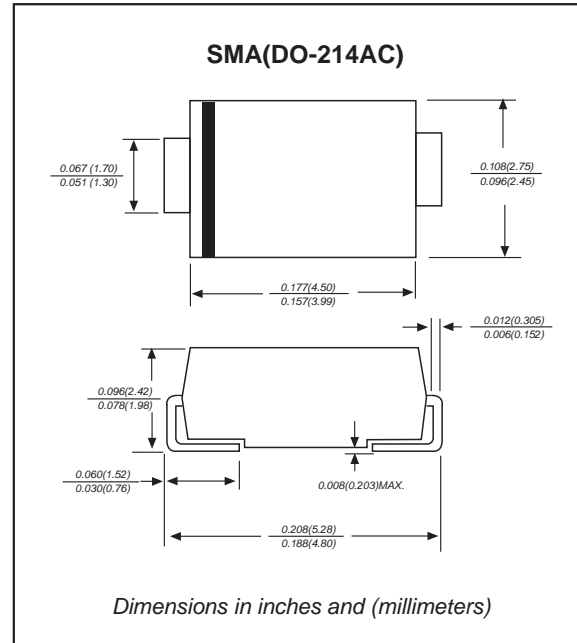
### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Super fast switching for high efficiency
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C/10 seconds at terminals
- ◆ Glass passivated chip junction
- ◆ Compliant to RoHS Directive 2011/65/EU

### Mechanical data

- ◆ **Case:** JEDEC DO-214AC molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

### Package outline

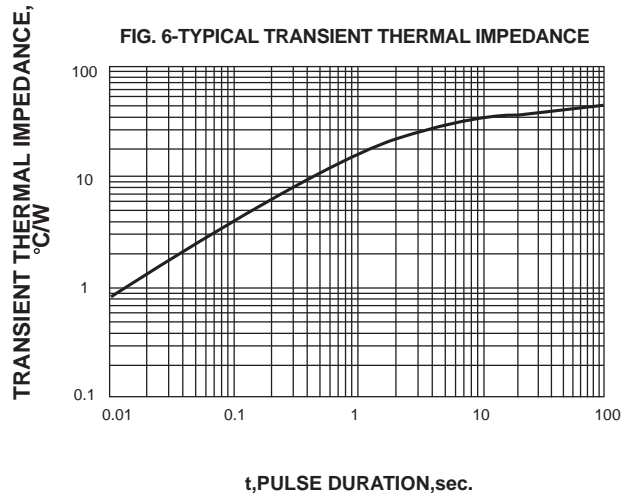
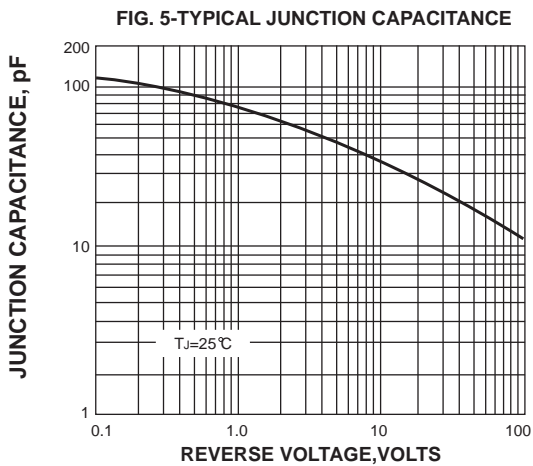
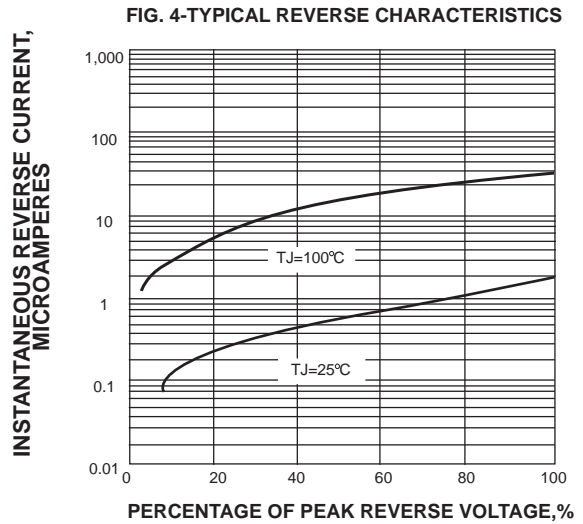
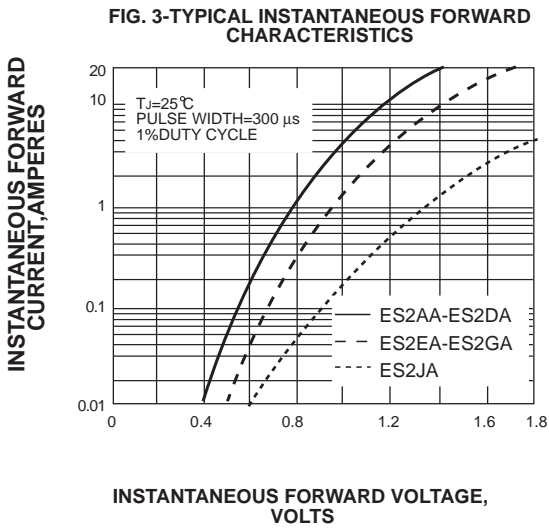
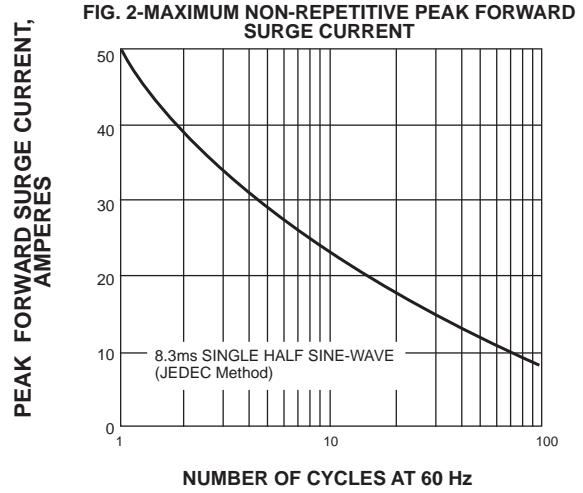
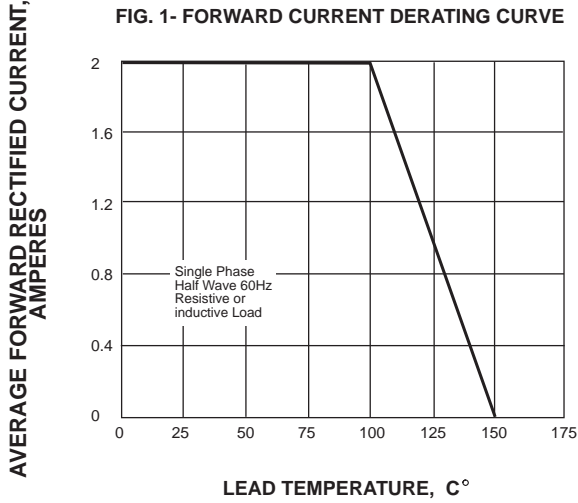


### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

	SYMBOLS	ES2AA	ES2BA	ES2CA	ES2DA	ES2EA	ES2GA	ES2JA	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	150	200	300	400	600	V
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	$V_{DC}$	50	100	150	200	300	400	600	V
Maximum average forward rectified current at $T_L=75^\circ\text{C}$	$I_{(AV)}$	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	50.0							A
Maximum instantaneous forward voltage at 2.0A	$V_F$	0.95			1.25		1.7		V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	$I_R$	5.0 50.0							$\mu\text{A}$
Maximum reverse recovery time (NOTE 1)	$t_{rr}$	35							ns
Typical junction capacitance (NOTE 2)	$C_J$	40.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	60.0							$^\circ\text{C/W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

- Note:**
1. Reverse recovery condition  $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$
  2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
  3. P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas

### Rating and characteristic curves



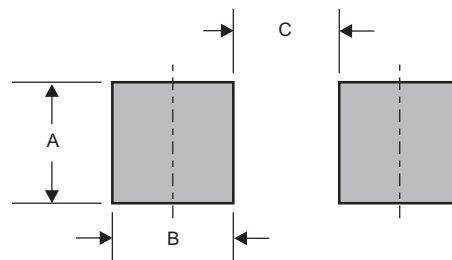
## Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

## Marking

Type number	Marking code
ES2AA	ES2A
ES2BA	ES2B
ES2CA	ES2C
ES2DA	ES2D
ES2EA	ES2E
ES2GA	ES2G
ES2JA	ES2J

## Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA/DO-214AC	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)

**Suggested thermal profiles for soldering processes**

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T <sub>L</sub> to T <sub>P</sub> )	<3°C/sec
Preheat -Temperature Min(T <sub>smin</sub> ) -Temperature Max(T <sub>smax</sub> ) -Time(min to max)(t <sub>s</sub> )	150°C 200°C 60~120sec
T <sub>smax</sub> to T <sub>L</sub> -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T <sub>L</sub> ) -Time(t <sub>L</sub> )	217°C 60~260sec
Peak Temperature(T <sub>P</sub> )	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t <sub>P</sub> )	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes